

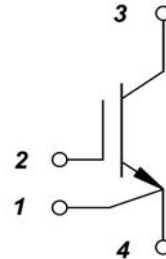
PRODUCT FEATURES

- IGBT³ Chip(Trench+Field Stop technology)
- Low switching losses
- Low saturation voltage and positive temperature coefficient
- Fast switching and short tail current
- Popular SOT-227 Package



APPLICATIONS

- AC motor control
- Motion/servo control
- Inverter and power supplies



IGBT

ABSOLUTE MAXIMUM RATINGS

T_C=25°C unless otherwise specified

Symbol	Parameter/Test Conditions		Values	Unit
V _{CES}	Collector Emitter Voltage	T _J =25°C	1200	V
V _{GES}	Gate Emitter Voltage		±20	
I _C	DC Collector Current	T _C =25°C	200	A
		T _C =80°C	150	
I _{CM}	Repetitive Peak Collector Current	tp=1ms	300	
P _{tot}	Power Dissipation Per IGBT		690	W

MODULE CHARACTERISTICS

T_C=25°C unless otherwise specified

Symbol	Parameter/Test Conditions		Values	Unit
T _{Jmax}	Max. Junction Temperature		150	°C
T _{Jop}	Operating Temperature		-40~150	
T _{stg}	Storage Temperature		-40~125	
V _{isol}	Isolation Breakdown Voltage	AC, 50Hz(R.M.S), t=1minute	3000	V
Torque	to heatsink	Recommended (M4)	0.7~1.1	Nm
	to terminal	Recommended (M4)	0.7~1.1	Nm
Weight			26.5	g

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**IGBT
ELECTRICAL CHARACTERISTICS**

T_C = 25°C unless otherwise specified

Symbol	Parameter/Test Conditions		Min.	Typ.	Max.	Unit	
V _{GE(th)}	Gate Emitter Threshold Voltage	V _{CE} =V _{GE} , I _C =6mA	5	5.8	6.5	V	
V _{CE(sat)}	Collector Emitter Saturation Voltage	I _C =150A, V _{GE} =15V, T _J =25°C		1.7	2.15		
		I _C =150A, V _{GE} =15V, T _J =125°C		1.9			
I _{CES}	Collector Leakage Current	V _{CE} =1200V, V _{GE} =0V, T _J =25°C			100	μA	
		V _{CE} =1200V, V _{GE} =0V, T _J =125°C			1	mA	
I _{GES}	Gate Leakage Current	V _{CE} =0V, V _{GE} =±15V, T _J =125°C	-400		400	nA	
R _{gint}	Integrated Gate Resistor			5		Ω	
Q _g	Gate Charge	V _{CE} =600V, I _C =150A, V _{GE} =15V		1.4		μC	
C _{ies}	Input Capacitance	V _{CE} =25V, V _{GE} =0V, f=1MHz		10.5		nF	
C _{res}	Reverse Transfer Capacitance				0.4		nF
t _{d(on)}	Turn on Delay Time	V _{CC} =600V, I _C =150A R _G =2.4Ω, V _{GE} =±15V, Inductive Load	T _J =25°C		260		ns
			T _J =125°C		290		ns
t _r	Rise Time		T _J =25°C		30		ns
			T _J =125°C		50		ns
t _{d(off)}	Turn off Delay Time	V _{CC} =600V, I _C =150A R _G =2.4Ω, V _{GE} =±15V, Inductive Load	T _J =25°C		420		ns
			T _J =125°C		520		ns
t _f	Fall Time		T _J =25°C		70		ns
			T _J =125°C		90		ns
E _{on}	Turn on Energy	V _{CC} =600V, I _C =150A R _G =2.4Ω, V _{GE} =±15V, Inductive Load	T _J =25°C		12		mJ
			T _J =125°C		16		mJ
E _{off}	Turn off Energy		T _J =25°C		11		mJ
			T _J =125°C		14.5		mJ
I _{sc}	Short Circuit Current	tpsc ≤ 10μS, V _{GE} =15V T _J =125°C, V _{CC} =600V		600		A	
R _{thJC}	Junction to Case Thermal Resistance (Per IGBT)				0.18	K /W	

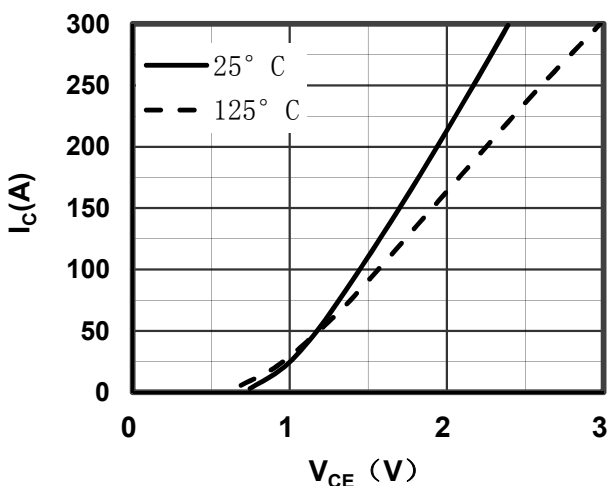


Figure 1. Typical Output Characteristics IGBT

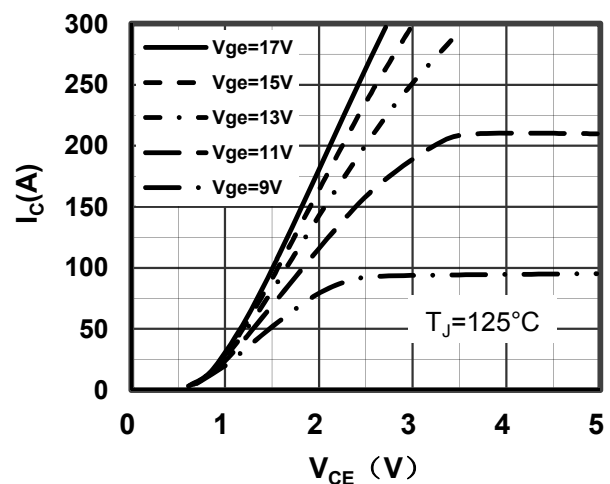


Figure 2. Typical Output Characteristics IGBT

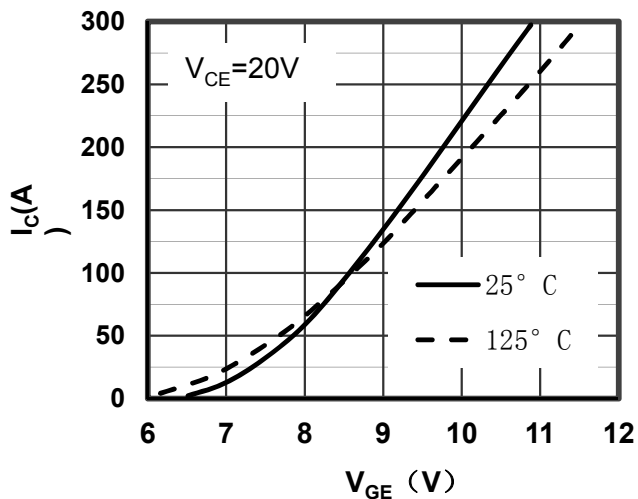


Figure 3. Typical Transfer characteristics IGBT

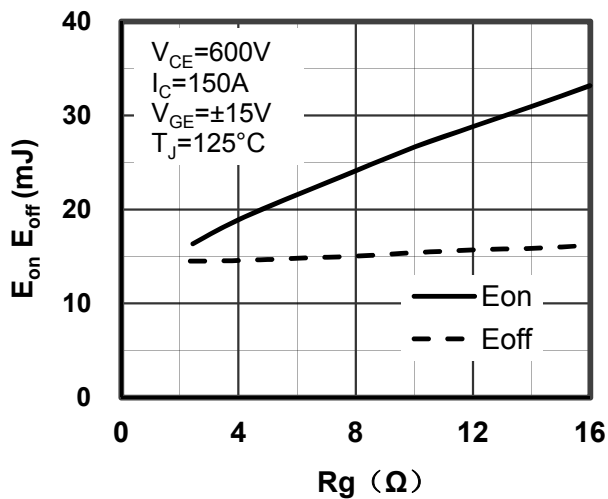


Figure 4. Switching Energy vs Gate Resistor IGBT

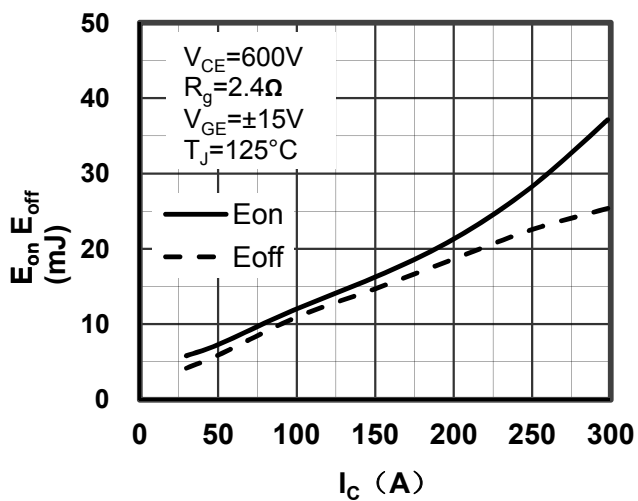


Figure 5. Switching Energy vs Collector Current IGBT

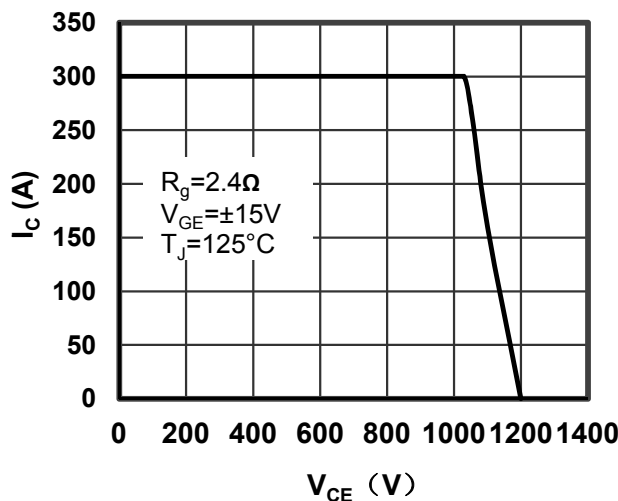


Figure 6. Reverse Biased Safe Operating Area IGBT

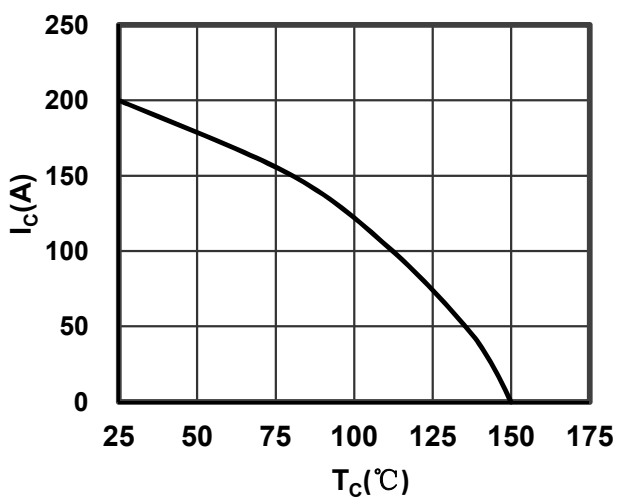


Figure 7. Collector Current vs Case temperature

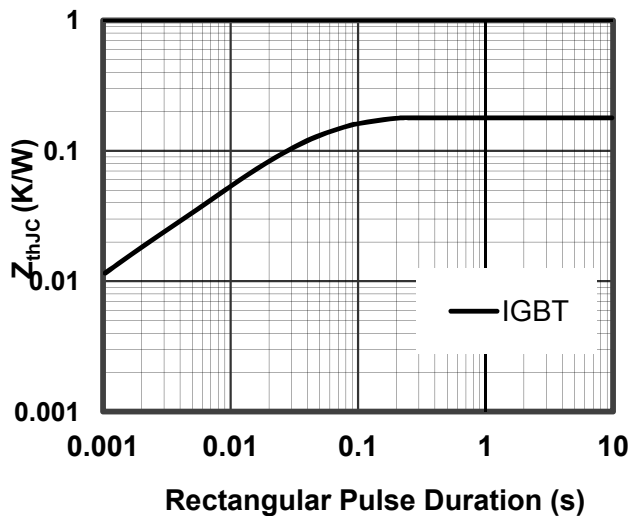
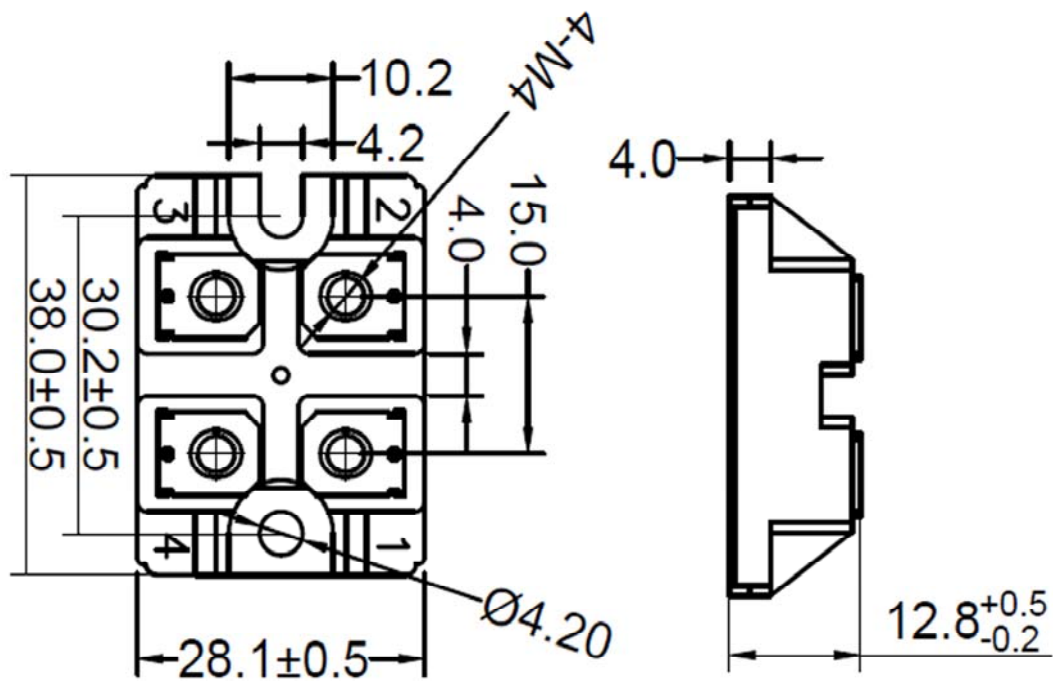


Figure 8. Transient Thermal Impedance of IGBT



Dimensions in (mm)
Figure 9. Package Outline